



Thermal Management of Electronic Packaging

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Deadline for manuscript
submissions:

closed (30 November 2022)

Message from the Guest Editors

This Special Issue focuses on innovative solutions, novel contributions, critical reviews, case studies, or theoretical models of Thermal Management of Electronic Packaging studies from microchip-level to room-level (including data center cooling solutions). The invited topics include, but are not limited to:

- thermodynamic (energy and exergy) analysis;
- heat transfer enhancement; system design and optimization;
- thermo- and/or techno-economic assessments of the air-cooled and liquid-cooled solutions;
- thermal energy store via sensible or latent heat mechanisms.





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Message from the Editor-in-Chief

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